

# ICCE 2014

The Fifth International Conference on Communications and Electronics  
(July 30<sup>th</sup> - August 1<sup>st</sup> 2014)

Da Nang, Vietnam

## CALL FOR PAPERS – Extended Deadline (<http://www.icce-2014.org>)

### General Co-Chairs

Nguyen Xuan Quynh  
National Council for Professor  
Titles, Vietnam

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University of Wuerzburg, Germany

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Queen's Univ. Belfast, UK

Lei Shu  
Guangdong Univ. of Petrochemical  
Tech., China

Thomas Magedanz  
TU Berlin, Germany

### IMPORTANT DATES

Extended hard deadline:

**February 21<sup>st</sup>, 2014**

Acceptance notification:

**April 18<sup>th</sup>, 2014**

Registration & camera-ready:

**May 2<sup>nd</sup>, 2014**

Conference date:

**July 30<sup>th</sup> – August 1<sup>st</sup> 2014**

### CONFERENCE OFFICIAL ADDRESS:

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The International Conference on Communications and Electronics (ICCE) is becoming a reputable bi-annual international conference series in the scientific community on the areas of Electronics and Communications recently. Following the past successful ICCE 2012, which received 237 submissions from 29 countries with the acceptance rate of 41%, the fifth ICCE (ICCE 2014) looks for significant contributions to various topics in communications engineering, networking, microwave engineering, signal processing and electronic engineering. The conference will also include tutorials, workshops, and technology panels given by world-class speakers.

### SUBMISSION AND PUBLICATIONS

All authors should prepare full version of papers with maximum length of 6 pages and submit via EDAS: <http://edas.info/N15665>. Full accepted papers will be published in the ICCE 2014 Conference Proceedings and submitted for inclusion in IEEE Xplore®. The proceedings of ICCE series is indexed by SCOPUS and listed in Conference Proceeding Citation Index (CPCI) of Thomson Reuters.

### SCOPE OF THE CONFERENCE

Contributed papers are solicited describing original works in electronics, communications engineering and related technologies. Topics and technical areas of interest include but are not limited to the following:

#### I. COMMUNICATION NETWORKS AND SYSTEMS

- *Networking*: Future Internet/Future Networks, Crowdsourcing, QoS/QoE and Resource Management, Green Networking, Optical Networks; Wireless, Mobile, Ad-hoc and Sensor Networks, Ubiquitous Networks and Internet of Things, Network Security.
- *Communication Systems*: Coding and Information Theory, Wireless, UWB, Ultrasonic Communications, Satellite Communications; Radio-over-Fiber, Free Space and Fiber-Optic Communications; Software Defined Radio, Cognitive Radio; Cooperative Communications, Secured Communication Systems, Multi-antenna Communication Systems.

#### II. SIGNAL PROCESSING AND APPLICATIONS

- Image, Audio, Video Processing, Analysis and Applications
- 3D Image Processing and Scene Analysis, Multiview Data Integration, 3D Scene or Model Reconstruction from Time-of-Flight Cameras.
- 3D Computer Vision Systems and Applications.
- Image Based Human-Computer Interaction.
- Biomedical Signal Processing and Analysis, Computer-Aided Diagnosis.
- Biomedical Applications in Molecular, Structural, and Function Imaging.
- PACS and Imaging Informatics.
- Ambient Intelligence.
- Signal Processing in GNSS.
- Signal Filtering, Detection and Estimation.
- Statistical Signal Processing and Modeling.

#### III. MICROWAVE ENGINEERING

- Microwave Devices/Components Design and Techniques: Passive, Active Devices, MEMS, Integration Techniques, Nano-Scale Devices, Millimeter-Wave and THz Components.
- Antenna and Propagation: Wideband, Multiband Antennas, Smart Antennas, Digital Beam Forming, MIMO, Antenna Modeling and Measurements, Phased Arrays, Channel Modeling and Propagation.
- EM Field Theory and Simulation Techniques: EM Field Theory, Numerical Techniques, Metamaterials, FSSs, Electromagnetic Bandgap Structures.
- RF, Microwave and Millimeterwave Systems and Applications.
- Other Related Technologies: Nanoscale Integration of Planar, Free-Space, and Mixed Subsystems.

#### IV. ELECTRONIC SYSTEMS

- Circuits and Design Techniques for Digital, Memory, Analog and Mixed-Signal Systems.
- Circuits and Design Techniques for High Performance and Low Power.
- System Design, Synthesis and Optimization; Formal Methods and Verification.
- Embedded Systems; Reliable and Reconfigurable System.
- Communication, Consumer and Multimedia System; Medical and Healthcare Systems.
- Spacecraft Avionics Systems and Applications

**SPECIAL SESSIONS:** ICCE 2014 offers special sessions, which provide an overview of the state-of-the-art and current research directions on communications and electronics. Please visit <http://www.icce-2014.org/> for more details.



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